



Ifw

PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Application of:

Name Savas et al

Serial No. 10/723,386

Filed: November 26, 2003

For: APPARATUS AND METHOD FOR LOW
TEMPERATURE STRIPPING OF PHOTORESIST
AND RESIDUES

Examiner: Not Yet Assigned

Art Group: 1752

Att. Docket No.: MAT-6

Date: June 22, 2004

CERTIFICATE OF MAILING I hereby certify that this correspondence is being deposited with the United States Postal Service as First Class Mail in an envelope addressed to: Commissioner of Patents, P.O. Box 1450, Alexandria, VA 22313-1450 on June 22, 2004.

Signed:

Jay R Beyer

Commissioner of Patents
P.O. Box 1450
Alexandria, VA 22313-1450

INFORMATION DISCLOSURE STATEMENT

Sir:

Enclosed is a copy of Information Disclosure Citation Form PTO-1449 together with copies of the non US patent documents cited on that form. It is respectfully requested that the cited documents be considered and that the enclosed copy of Information Disclosure Citation Form PTO-1449 be initialed by the Examiner to indicate such consideration and a copy thereof returned to applicant(s).

Pursuant to 37 C.F.R. § 1.97, the submission of this Information Disclosure Statement is not to be construed as a representation that a search has been made and is not to be construed as an admission that the information cited in this statement is material to patentability.

Pursuant to 37 C.F.R. § 1.97, this Information Disclosure Statement is being submitted under one of the following (as indicated by an "X" to the left of the appropriate paragraph):

X 37 C.F.R. §1.97(b).

37 C.F.R. §1.97(c). If so, then enclosed with this Information Disclosure Statement is one of the following:

A certification pursuant to 37 C.F.R. §1.97(e) or

A check for \$___ for the fee under 37 C.F.R. § 1.17(p).

37 C.F.R. §1.97(d). If so, then enclosed with this Information Disclosure Statement are the following:

(1) A certification pursuant to 37 C.F.R. §1.97(e);

(2) A petition requesting consideration of the Information Disclosure Statement; and

(3) Please charge Deposit Account No. 19-1685 (Order No. MAT-6) \$___ for the fee under 37 C.F.R. §1.17(i) for submission of the Information Disclosure Statement. (a duplicate copy of this sheet is enclosed)

If there are any additional charges, please charge Deposit Account No. 19-1685 (Order No. MAT-6).

Respectfully submitted,

Jay R Beyer

Registration No. 39,907

Form 1449 (Modified)

Atty Docket No.

Serial No.:

Information Disclosure
Statement By Applicant

MAT-6

10/723,386

Applicants:

Savas, et al

Filing Date

November 26, 2003

Group

1752

Use Several Sheets if Necessary)



U.S. Patent Documents

Examiner Initial	No.	Patent No.	Date	Patentee	Class	Sub- class	Filing Date
	A	4,028,135	6/7/1977	Vig et al			
	B	4,782,267	11/1/1988	Collins et al			
	C	5,234,540	8/10/1993	Grant et al			
	D	5,954,884	11/21/1999	Lawing et al			
	E	6,015,503	1/18/2000	Butterbaugh et al			
	F	6,124,211	11/26/2000	Butterbaugh et al			
	G	US 6,183,566 B1	2/6/2001	Lawing et al			
	H	US 6,277,767 B1	8/21/2001	Shiramizu et al			

Foreign Patent or Published Foreign Patent Application

Examiner Initial	No.	Document No.	Publication Date	Country or Patent Office	Class	Sub- class	Translation	
							Yes	No
	I							
	J							
	K							

Other Documents

Examiner	No.	Author, Title, Date, Place (e.g. Journal) of Publication
Initial		
	L	Torek et al; UV/Fluorine Etching of Native Silicon Oxides; 1992; Proceedings of the Second International Symposium on Cleaning Technology in Semiconductor Device Manufacturing; pp 80-86.
	M	Ito et al; Wafer Purification by Photochemical Dry Cleaning; March 1989, Semiconductor World; pp120-123
	N	Zhang et al; Large Area Photochemical Dry Etching of Polyimide; 1993; Applied Surface Science; Vol 69; pp 299-304
	O	Vig; Ultraviolet-Ozone Cleaning of Semiconductor Surfaces; January 1992; US Army Laboratory Command (LAPCOM) Technical Report
Examiner		Date Considered

Examiner: Initial citation considered. Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.